



SY56034AR

Low Voltage 1.2V/1.8V/2.5V 2:6 MUX with
Crosspoint Capability 5GHz/6.4Gbps

General Description

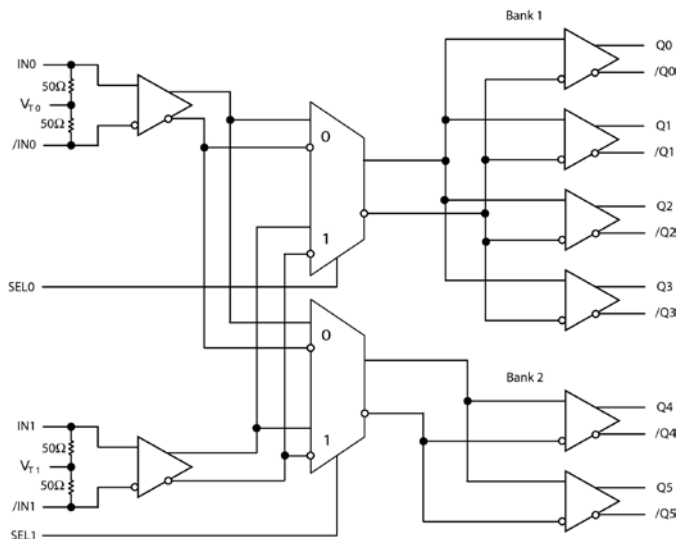
The SY56034AR is a fully differential, low voltage 1.2V/1.8V/2.5V CML 2:6 (2+4) MUX with crosspoint capability. The SY56034AR can process clock signals as fast as 5GHz or data patterns up to 6.4Gbps.

The differential input includes Micrel's unique, 3-pin input termination architecture that interfaces to LVPECL, LVDS or CML differential signals as small as 100mV (200mV_{pp}) without any level-shifting or termination resistor networks in the signal path. For AC-coupled input interface applications, an internal voltage reference is provided to bias the V_T pin. The outputs are 400mV CML, with extremely fast rise/fall times guaranteed to be less than 80ps.

The SY56034AR operates from a 2.5V ±5% core supply and a 1.2V/1.8V/2.5V ±5% output supply and is guaranteed over the full industrial temperature range (-40°C to +85°C). The SY56034AR is part of Micrel's high-speed, Precision Edge[®] product line.

Datasheets and support documentation can be found on Micrel's web site at: www.micrel.com.

Functional Block Diagram



Precision Edge is a registered trademark of Micrel, Inc.



Precision Edge[®]

Features

- 1.2V/1.8V/2.5V CML 2:6 (2+4) MUX with Crosspoint Capability
- Guaranteed AC performance over temperature and voltage:
 - DC-to- > 6.4Gbps throughput
 - <300ps propagation delay (IN-to-Q)
 - <25ps Output skew
 - <80ps rise/fall times
- Ultra-low jitter design
 - <1p_SRMS cycle-to-cycle jitter
 - <10p_SPP total jitter
 - <1p_SRMS random jitter
 - <10p_SPP deterministic jitter
- High-speed CML outputs
- 2.5V ±5% , 1.2V/1.8V/2.5V ±5% power supply operation
- Industrial temperature range: -40°C to +85°C
- Available in 32-pin QFN package

Applications

- Data Distribution: OC-48, OC-48+FEC
- SONET clock and data distribution
- Fibre Channel clock and data distribution
- Gigabit Ethernet clock and data distribution

Markets

- Storage
- ATE
- Test and measurement
- Enterprise networking equipment
- High-end servers
- Access
- Metro area network equipment

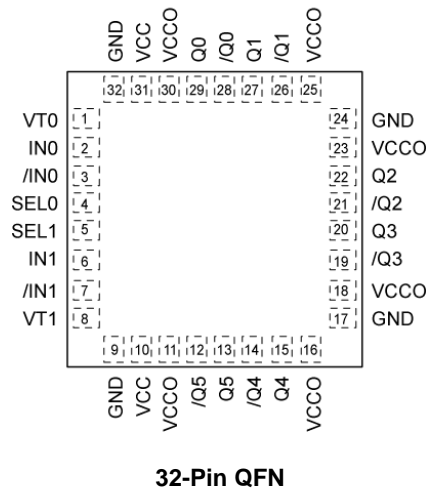
Ordering Information⁽¹⁾

Part Number	Package Type	Operating Range	Package Marking	Lead Finish
SY56034ARMG	QFN-32	Industrial	56034AR with Pb-Free bar-line indicator	NiPdAu Pb-Free
SY56034ARMGTR ⁽²⁾	QFN-32	Industrial	56034AR with Pb-Free bar-line indicator	NiPdAu Pb-Free

Notes:

1. Contact factory for die availability. Dice are guaranteed at T_A = 25°C, DC Electricals only.
2. Tape and Reel.

Pin Configuration



Truth Table

SEL0	SEL1	Bank1	Bank2
L	L	IN0	IN0
L	H	IN0	IN1
H	L	IN1	IN0
H	H	IN1	IN1

Pin Description

Pin Number	Pin Name	Pin Function
2,3 6,7	IN0, /IN0 IN1, /IN1	Differential Inputs: These input pairs are the differential signal inputs to the device. They accept differential signals as small as 100mV (200mV _{PP}). Each input pin internally terminates with 50Ω to the VT pin.
1 8	VT0 VT1	Input Termination Center-Tap: Each side of the differential input pair terminates to a VT pin. This pin provides a center-tap to a termination network for maximum interface flexibility. An internal high impedance resistor divider biases VT to allow input AC-coupling. For AC-coupling, bypass VT with a 0.1μF low ESR capacitor to VCC. See "Interface Applications" subsection and Figure 2a.
4 5	SEL0 SEL1	These single-ended TTL/CMOS-compatible inputs select the inputs to the crosspoint switch. Note that each of these inputs is internally connected to a 25kΩ pull-up resistor and will default to a logic HIGH state if left open.
10, 31	VCC	Positive Power Supply: Bypass with 0.1μF//0.01μF low ESR capacitors as close to the V _{CC} pin as possible. Supplies input and core circuitry.
11,16,18, 23,25,30	VCCO	Output Supply: Bypass with 0.1μF//0.01μF low ESR capacitors as close to the V _{CCO} pins as possible. Supplies the output buffer.
9,17,24,32	GND, Exposed pad	Ground: Exposed pad must be connected to a ground plane that is the same potential as the ground pin.
29,28 27,26 22,21 20,19 15,14 13,12	Q0, /Q0 Q1, /Q1 Q2, /Q2 Q3, /Q3 Q4, /Q4 Q5, /Q5	CML Differential Output Pairs: Differential buffered copy of the selected input signal. The output swing is typically 390mV. See "Interface Applications" subsection for termination information. Output pairs Q0 to Q3 belong to Bank 1. Q4 and Q5 belong to Bank 2.

Absolute Maximum Ratings⁽¹⁾

Supply Voltage (V_{CC}) -0.5V to +3.0V
 Supply Voltage (V_{CCO}) -0.5V to +2.7V
 $V_{CC} - V_{CCO}$ <1.8V
 $V_{CCO} - V_{CC}$ <0.5V
 Input Voltage (V_{IN}) -0.5V to $V_{CC} + 0.5V$
 CML Output Voltage (V_{OUT}) 0.6V to $V_{CCO} + 0.5V$
 Current (I_T)
 Source or sink current on VT pin $\pm 100mA$
 Input Current
 Source or sink current on (IN, /IN) $\pm 50mA$
 Maximum operating Junction Temperature 125°C
 Lead Temperature (soldering, 20sec.) 260°C
 Storage Temperature (T_s) -65°C to +150°C

Operating Ratings⁽²⁾

Supply Voltage (V_{CC}) 2.375V to 2.625V
 (V_{CCO}) 1.14V to 2.625V
 Ambient Temperature (T_A) -40°C to +85°C
 Package Thermal Resistance⁽³⁾
 QFN
 Still-air (θ_{JA}) 50°C/W
 Junction-to-board (ψ_{JB}) 20°C/W

DC Electrical Characteristics⁽⁴⁾

$T_A = -40^\circ C$ to $+85^\circ C$, unless otherwise stated.

Symbol	Parameter	Condition	Min	Typ	Max	Units
V_{CC}	Power Supply Voltage Range	V_{CC}	2.375	2.5	2.625	V
		V_{CCO}	1.14	1.2	1.26	V
		V_{CCO}	1.7	1.8	1.9	V
		V_{CCO}	2.375	2.5	2.625	V
I_{CC}	Power Supply Current	Max. V_{CC}		100	140	mA
I_{CCO}	Power Supply Current	No Load. Max V_{CCO}		96	126	mA
R_{IN}	Input Resistance (IN-to- V_T , /IN-to- V_T)		45	50	55	Ω
R_{DIFF_IN}	Differential Input Resistance (IN-to-/IN)		90	100	110	Ω
V_{IH}	Input HIGH Voltage (IN, /IN)	IN, /IN	1.2		V_{CC}	V
V_{IL}	Input LOW Voltage (IN, /IN)	V_{IL} with $V_{IH} = 1.2V$	0.2		$V_{IH} - 0.1$	V
V_{IH}	Input HIGH Voltage (IN, /IN)	IN, /IN	1.14		V_{CC}	V
V_{IL}	Input LOW Voltage (IN, /IN)	V_{IL} with $V_{IH} = 1.14V$ (1.2V-5%)	0.66		$V_{IH} - 0.1$	V
V_{IN}	Input Voltage Swing (IN, /IN)	see Figure 3a	0.1		1.0	V
V_{DIFF_IN}	Differential Input Voltage Swing (IN - /IN)	see Figure 3b	0.2		2.0	V
V_{T_IN}	Voltage from Input to V_T				1.28	V

Notes:

1. Permanent device damage may occur if absolute maximum ratings are exceeded. This is a stress rating only and functional operation is not implied at conditions other than those detailed in the operational sections of this data sheet. Exposure to absolute maximum ratings conditions for extended periods may affect device reliability.
2. The data sheet limits are not guaranteed if the device is operated beyond the operating ratings.
3. Package thermal resistance assumes exposed pad is soldered (or equivalent) to the device's most negative potential on the PCB. ψ_{JB} and θ_{JA} values are determined for a 4-layer board in still-air number, unless otherwise stated. The circuit is designed to meet the DC specifications shown in the above table after thermal equilibrium has been established.
4. The circuit is designed to meet the DC specifications shown in the above table after thermal equilibrium has been established.

CML Outputs DC Electrical Characteristics⁽⁵⁾

$V_{CCO} = 1.14V$ to $1.26V$, $R_L = 50\Omega$ to V_{CCO} ,

$V_{CCO} = 1.7V$ to $1.9V$, $2.375V$ to $2.625V$, $R_L = 50\Omega$ to V_{CCO} or 100Ω across the outputs.

$V_{CC} = 2.375V$ to $2.625V$. $T_A = -40^\circ C$ to $+85^\circ C$, unless otherwise stated.

Symbol	Parameter	Condition	Min	Typ	Max	Units
V_{OH}	Output HIGH Voltage	$R_L = 50\Omega$ to V_{CCO}	$V_{CCO}-0.020$	$V_{CCO}-0.010$	V_{CCO}	V
V_{OUT}	Output Voltage Swing	See Figure 3a	300	390	475	mV
V_{DIFF_OUT}	Differential Output Voltage Swing	See Figure 3b	600	780	950	mV
R_{OUT}	Output Source Impedance		45	50	55	Ω

LVTTL/CMOS DC Electrical Characteristics⁽⁵⁾

$V_{CC} = 2.5V \pm 5\%$. $T_A = -40^\circ C$ to $+85^\circ C$, unless otherwise stated.

Symbol	Parameter	Condition	Min	Typ	Max	Units
V_{IH}	Input HIGH Voltage		2.0		V_{CC}	V
V_{IL}	Input LOW Voltage				0.8	V
I_{IH}	Input HIGH Current		-125		30	μA
I_{IL}	Input LOW Current		-300			μA

Note:

5. The circuit is designed to meet the DC specifications shown in the above table after thermal equilibrium has been established.

AC Electrical Characteristics

$V_{CC0} = 1.14V$ to $1.26V$, $R_L = 50\Omega$ to V_{CC0} ,

$V_{CC0} = 1.7V$ to $1.9V$, $2.375V$ to $2.625V$, $R_L = 50\Omega$ to V_{CC0} or 100Ω across the outputs.

$V_{CC} = 2.375V$ to $2.625V$. $T_A = -40^\circ C$ to $+85^\circ C$, unless otherwise stated.

Symbol	Parameter	Condition	Min	Typ	Max	Units
f_{MAX}	Maximum Frequency	NRZ Data	6.4			Gbps
		$V_{OUT} > 200mV$ Clock	5			GHz
t_{PD}	Propagation Delay	IN-to-Q Figure 1	150	220	300	ps
		SEL-to-Q Figure 1	100	200	300	ps
t_{Skew}	Input-to-Input Skew	Note 6		5	15	ps
	Output-to-Output skew	Note 7, All Outputs or Q0-Q3		7	25	ps
	Output-to-Output skew	Note 7, Q4-Q5		4	20	ps
	Part-to-Part Skew	Note 8			75	ps
t_{Jitter}	Data Random Jitter	Note 9			1	psRMS
	Deterministic Jitter	Note 10			10	psPP
	Clock Cycle-to-Cycle Jitter	Note 11			1	psRMS
	Total Jitter	Note 12			10	psPP
	Crosstalk Induced Jitter (Adjacent Channel)	Note 13			0.7	psPP
t_R, t_F	Output Rise/Fall Times (20% to 80%)	At full output swing.	20	60	80	ps
	Duty Cycle	$\leq 4GHz$ Differential I/O	47		53	%
		$< 5GHz$ Differential I/O	45		55	%

Notes:

- Input-to-Input skew is the difference in time between both inputs, measured at the same output, for the same temperature, voltage and transition.
- Output-to-Output skew is the difference in time between both outputs, receiving data from the same input, for the same temperature, voltage and transition.
- Part-to-part skew is defined for two parts with identical power supply voltages at the same temperature and no skew at the edges at the respective inputs.
- Random jitter is measured with a K28.7 pattern, measured at $\leq f_{MAX}$.
- Deterministic jitter is measured at 2.5Gbps with both K28.5 and $2^{23}-1$ PRBS pattern.
- Cycle-to-cycle jitter definition: the variation period between adjacent cycles over a random sample of adjacent cycle pairs. $t_{JITTER_CC} = T_n - T_{n+1}$, where T is the time between rising edges of the output signal.
- Total jitter definition: with an ideal clock input frequency of $\leq f_{MAX}$ (device), no more than one output edge in 10^{12} output edges will deviate by more than the specified peak-to-peak jitter value.
- Crosstalk-induced jitter is defined as the added jitter that results from signals applied to the adjacent channel. It is measured at the output while applying a similar, differential clock frequency to both inputs that is asynchronous with respect to each other.

Interface Applications

For Input Interface Applications, see Figures 4a through 4f. For CML Output Termination, see Figures 5a through Figure 5d.

CML Output Termination with VCCO 1.2V

For VCCO of 1.2V, Figure 5a, terminate the output with 50Ω-to-1.2V, DC coupled, not 100Ω differentially across the outputs.

If AC-coupling is used, Figure 5d, terminate into 50Ω -to-1.2V before the coupling capacitor and then connect to a high value resistor to a reference voltage.

Do not AC couple with internally terminated receiver. For example, 50 ANY -IN input. AC-coupling will offset the output voltage by 200mV and this offset voltage will be too low for proper driver operation. Any unused output pair needs to be terminated when VCCO is 1.2V, do not leave floating.

CML Output Termination with VCCO 1.8V, 2.5V

For VCCO of 1.8V or 2.5V, Figure 5a and Figure 5b, terminate with either 50Ω-to-1.8V or 100Ω differentially across the outputs. AC- or DC-coupling is fine. See Figure 5c for AC-coupling.

Input AC-Coupling

The SY56034AR input can accept AC-coupling from any driver. Bypass VT with a 0.1μF low ESR capacitor to VCC as shown in Figures 4c and 4d. VT has an internal high impedance resistor divider as shown in Figure 2a, to provide a bias voltage for AC-coupling.

Timing Diagrams

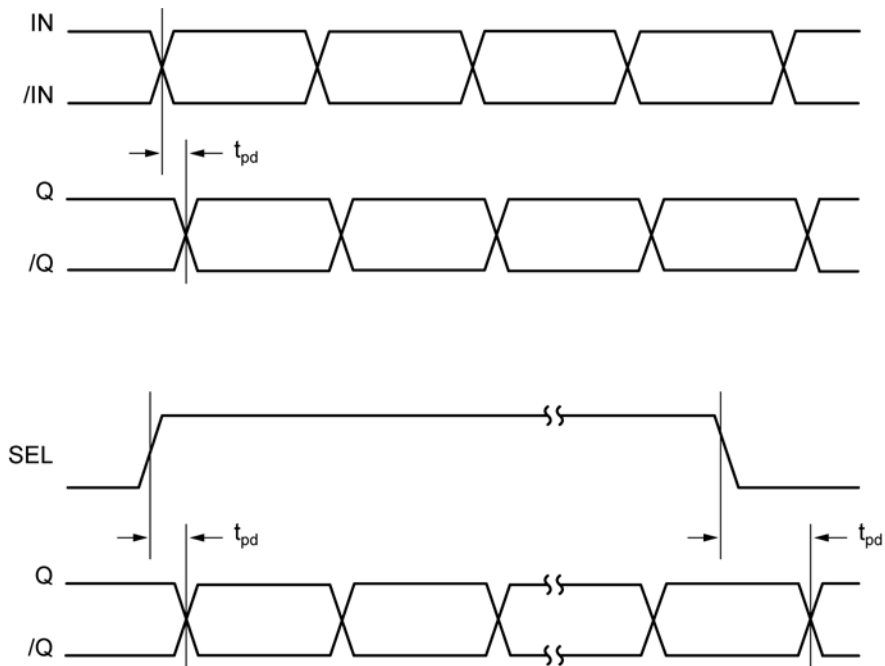
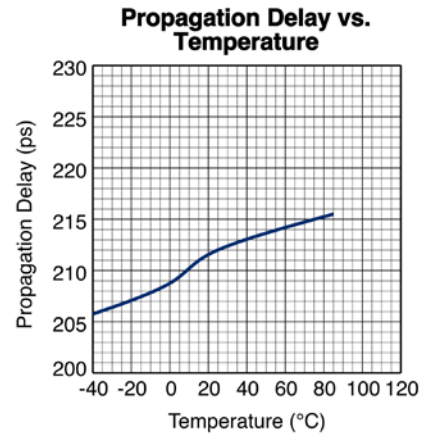
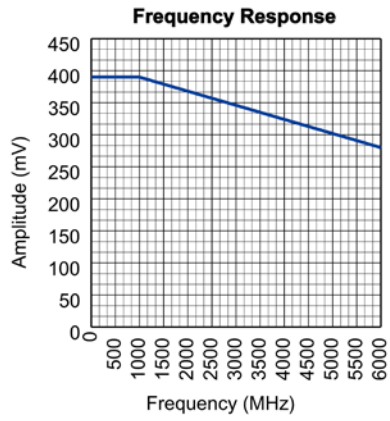


Figure 1. Propagation Delay

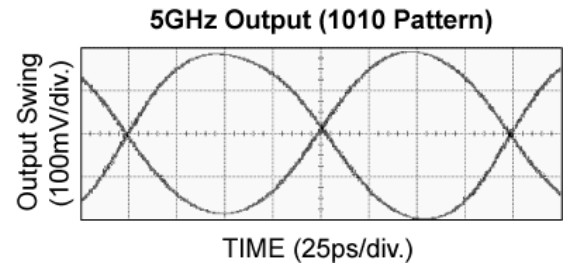
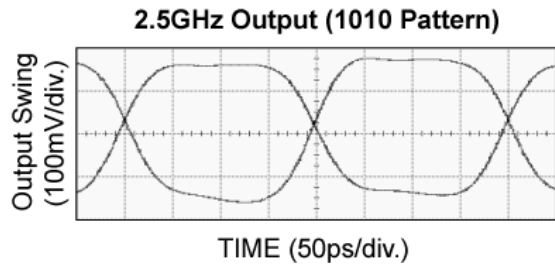
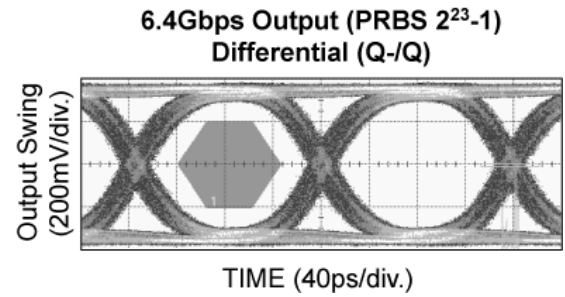
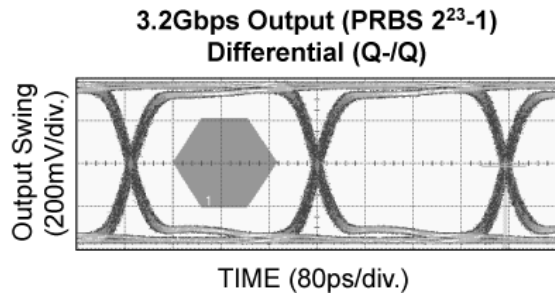
Typical Characteristics

$V_{CC} = 2.5V$, $V_{CC0} = 1.2V$, $GND = 0V$, $V_{IN} = 100mV$, $R_L = 50\Omega$ to $1.2V$, $T_A = 25^\circ C$, unless otherwise stated.



Functional Characteristics

$V_{CC} = 2.5V$, $V_{CCO} = 1.2V$, $GND = 0V$, $V_{IN} = 400mV$, $R_L = 50\Omega$ to $1.2V$, $T_A = 25^\circ C$, unless otherwise stated.



Input and Output Stage

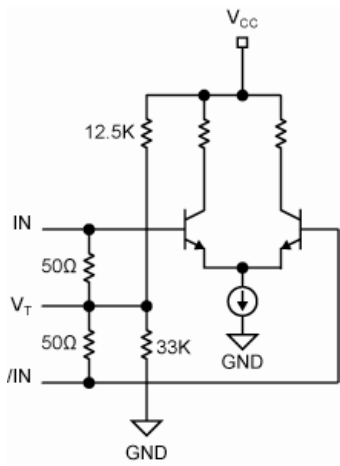


Figure 2a. Simplified Differential Input Buffer

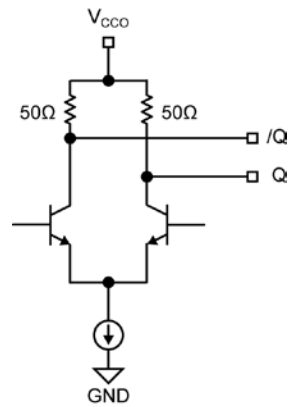


Figure 2b. Simplified CML Output Buffer

Single-Ended and Differential Swings



Figure 3a. Single-Ended Swing

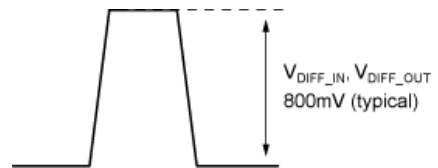


Figure 3b. Differential Swing

Input Interface Applications

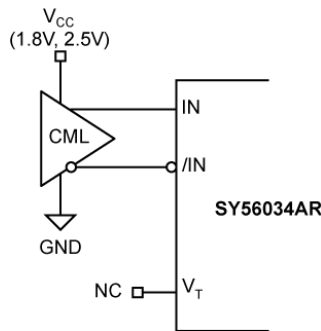


Figure 4a. CML Interface (DC-Coupled, 1.8V, 2.5V)
Option: V_T may be connected to V_{CC}

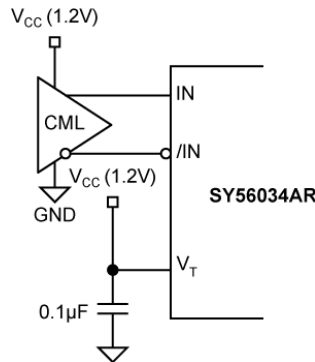


Figure 4b. CML Interface (DC-Coupled, 1.2V)

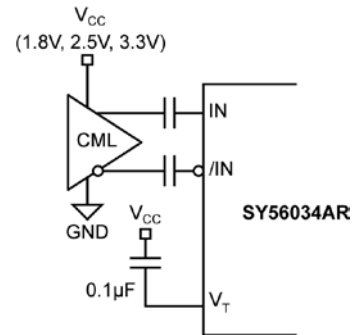


Figure 4c. CML Interface (AC-Coupled)

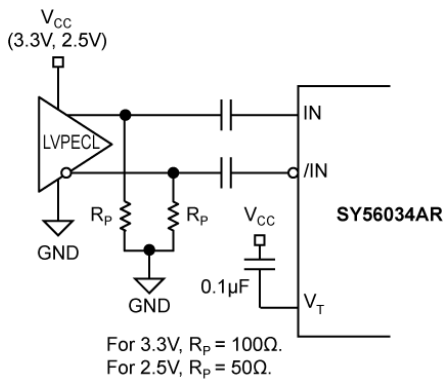


Figure 4d. LVPECL Interface (AC-Coupled)

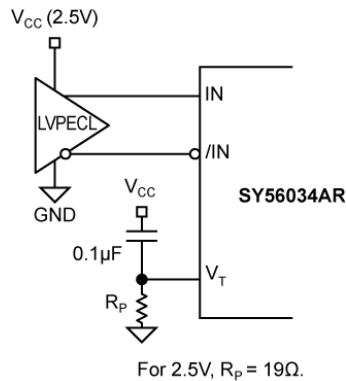


Figure 4e. LVPECL Interface (DC-Coupled)

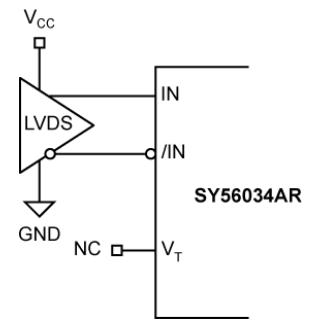
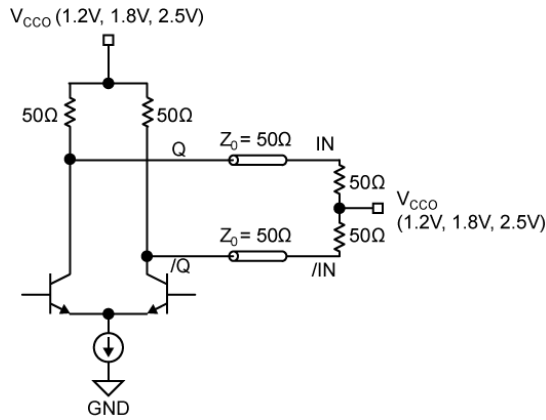
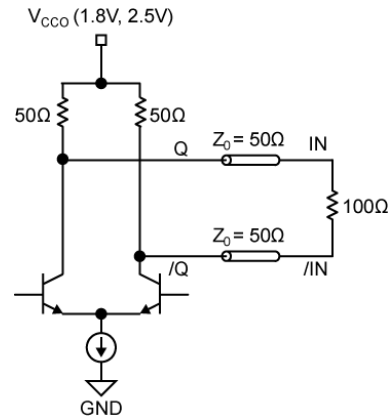


Figure 4f. LVDS Interface

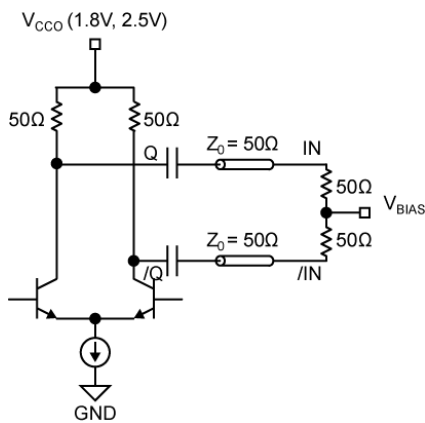
CML Output Termination



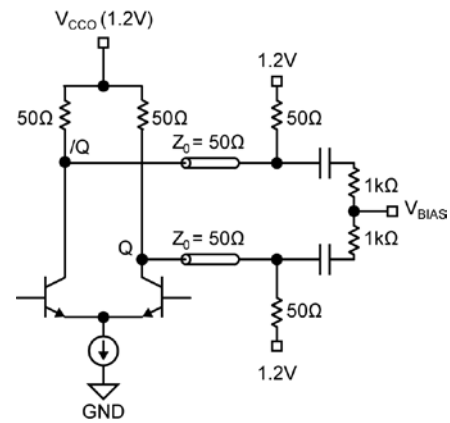
**Figure 5a. 1.2V 1.8V or 2.5V
CML DC-Coupled Termination**



**Figure 5b. 1.8V or 2.5V
CML DC-Coupled Termination**



**Figure 5c. CML AC-Coupled Termination
(Vcco 1.8V or 2.5V only)**

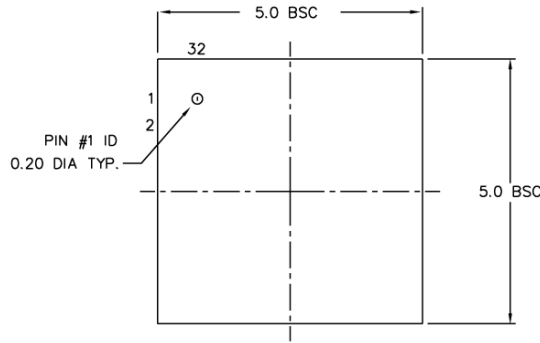


**Figure 5d. CML AC-Coupled Termination
(Vcco 1.2V only)**

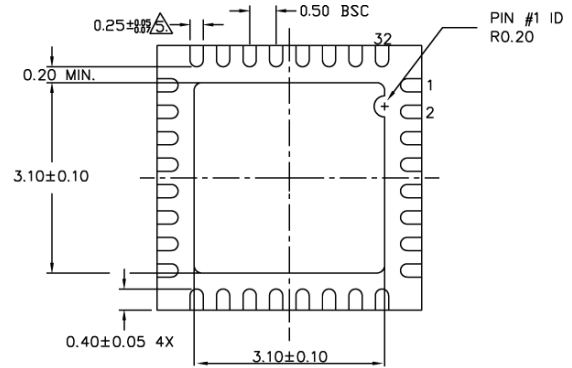
Related Product and Support Documents

Part Number	Function	Datasheet Link
HBW Solutions	New Products and Termination Application Notes	http://www.micrel.com/page.do?page=/product-info/as/HBWsolutions.shtml

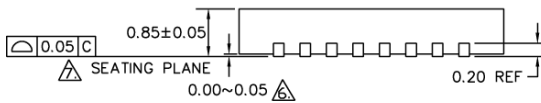
Package Information



TOP VIEW



BOTTOM VIEW



SIDE VIEW

NOTE:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
 2. MAX. PACKAGE WARPAGE IS 0.05 mm.
 3. MAXIMUM ALLOWABLE BURRS IS 0.076 mm IN ALL DIRECTIONS.
 4. PIN #1 ID ON TOP WILL BE LASER/INK MARKED.
- △ DIMENSION APPLIES TO METALIZED TERMINAL AND IS MEASURED BETWEEN 0.20 AND 0.25 mm FROM TERMINAL TIP.
- △ APPLIED ONLY FOR TERMINALS.
- △ APPLIED FOR EXPOSED PAD AND TERMINALS.

32-Pin QFN

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